

V-Chip Memory Back-Up Capacitors

NEZVN & NEZVL Series

FEATURES

- DOUBLE LAYER CONSTRUCTION
- HIGH TEMPERATURE REFLOW (+260°C)
- SURFACE MOUNTABLE V-CHIP STYLE
- EXTENDED TEMPERATURE RANGE (UP TO +85°C FOR NEZVL)

RoHS
Compliant
includes all homogeneous materials



CHARACTERISTICS

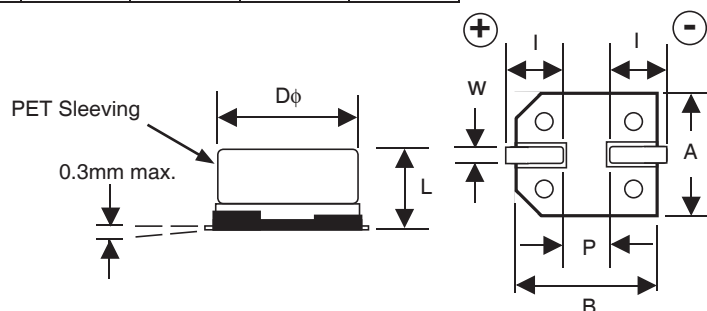
Series				NEZVN		NEZVL	
Operating Temperature Range				-25°C ~ +70°C		-40°C ~ +85°C	
Rated Capacitance Range				0.047F (47,000μF), 0.1F (100,000μF) and 0.22F (220,000μF)			
Capacitance Tolerance				+80%/-20% (Z)			
Rated Voltage Range				5.5VDC			
Load Life Test 1,000 hours	NEZVN @ +70°C NEZVL @ +85°C		Δ Capacitance Change		Less than ±30% of initial measured value		
			Maximum ESR		Less than 400% of the specified maximum value		
			Maximum Leakage Current		Less than 200% of the specified maximum value		
Characteristics at High & Low Temperature	NEZVN @ -25°C ~ +70°C		Δ Capacitance Change		Less than ±30% of 20°C value		
			Maximum ESR		Less than 500% of 20°C value		
			Maximum Leakage Current		Less than 400% of 20°C value		
	NEZVL @ -40°C ~ +85°C		Δ Capacitance Change		Less than ±30% of 20°C value		
			Maximum ESR	-40°C	Less than 700% of 20°C value		
				-25°C/+85°C	Less than 500% of 20°C value		
			Maximum Leakage Current		Less than 400% of the specified maximum value		
Vibration 10 ~ 55Hz (1 min./sweep) Total Amplitude 1.5mm, 2Hr in XYZ Directon		Δ Capacitance Change		Less than ±10% of initial measured value			
		Maximum ESR		Less than initial specified maximum value			
		Maximum Leakage Current		Less than initial specified maximum value			
Resistance to Soldering Heat Peak Temp. +260°C (Time over +230°C <30 seconds)		Δ Capacitance Change		Less than ±10% of initial measured value			
		Maximum ESR		Less than initial specified maximum value			
		Maximum Leakage Current		Less than initial specified maximum value			

STANDARD VALUES AND SPECIFICATIONS

NIC P/N	Capacitance Value (F)	Working Voltage (VDC)	Holding Voltage (VDC min.)	Max. Leakage Current after 30 minutes (μA)	Max. ESR @ 1KHz (Ω)
NEZVN473Z5.5V12.5X8.5F	0.047	5.5	4.0	69	30
NEZVN104Z5.5V12.5X8.5F	0.1	5.5	4.0	100	30
NEZVN224Z5.5V12.5X8.5F	0.22	5.5	4.0	135	30
NEZVL473Z5.5V12.5X10.5F	0.047	5.5	4.0	69	45
NEZVL104Z5.5V12.5X10.5F	0.1	5.5	4.0	100	45
NEZVL224Z5.5V12.5X10.5F	0.22	5.5	4.0	135	45

CASE DIMENSIONS (mm)

Case Size	Dφ ± 0.5	L max.	A/B ± 0.2	I	W	P
12.5X8.5	12.5	8.5	13.0	5.0	1.2	5.0
12.5X10.5	12.5	10.5	13.0	5.0	1.2	5.0



PRECAUTIONS

WASHING is NOT RECOMMENDED. Additional precautions can be found at www.niccomp.com/precautions
If in doubt or uncertainty, please review your specific application - process details with NIC's technical support personnel: tpmg@niccomp.com

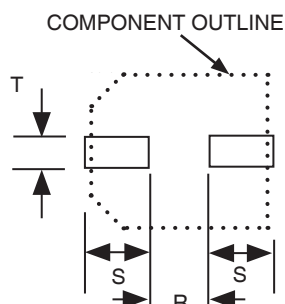


NIC COMPONENTS CORP. www.niccomp.com | www.lowESR.com | www.RFpassives.com | www.SMTmagnetics.com

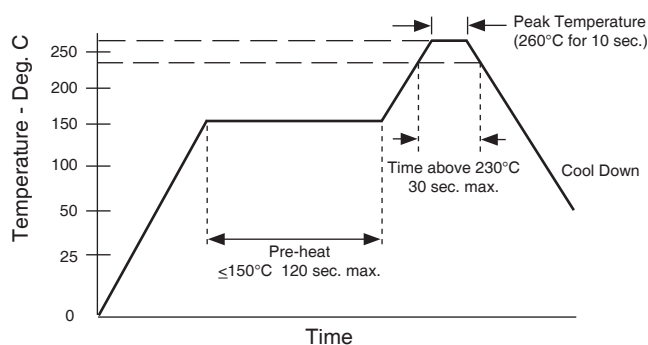
SPECIFICATIONS ARE SUBJECT TO CHANGE

LAND PATTERN DIMENSIONS (mm)

Case Diameter	R	S	T
12.5	4.0	6.0	3.2

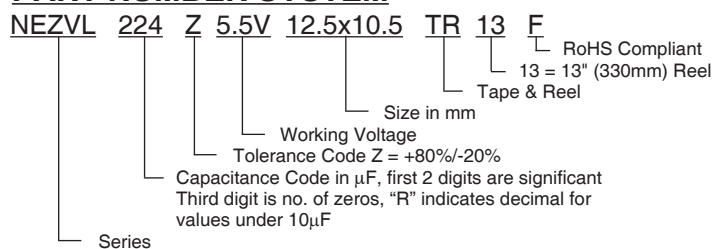


STANDARD RECOMMENDED REFLOW PROFILE



1. The temperatures shown are the surface temperature values on the top of the can and on the capacitor terminals.
2. 2x reflow process maximum. Capacitor should be allowed to return to room temperature before second reflow process.

PART NUMBER SYSTEM

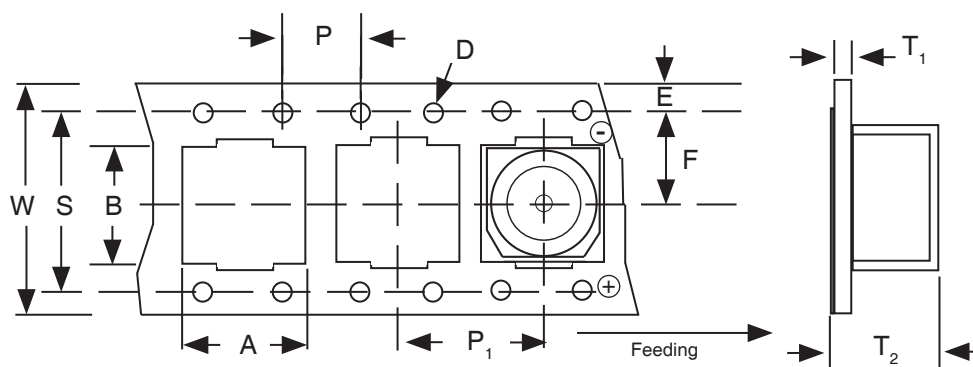


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CARRIER TAPE DIMENSIONS (mm)

Case Size	A ± 0.2	B ± 0.2	D +1/-0	E ± 0.1	F ± 0.1	P ± 0.1	P ₁ ± 0.1	T ₁ ± 0.1	T ₂ ± 0.2	W ± 0.3	Quantity/Reel
12.5 x 8.5	13.4	13.4	1.50	1.75	11.5	4.0	24.0	0.5	9.5	32.0	300
12.5 x 10.5	11.4	13.0	1.50	1.75	11.5	4.0	24.0	0.5	11.0	32.0	250



REEL DIMENSIONS (mm)

Case Diameter	A max.	B min.	C ± 0.5	W	t
12.5	$\phi 322$	$\phi 80$	13.0	32.0	3.0

